

1                   ABSTRACT OF THE DISCLOSURE

2                   In one aspect, the invention includes a method of encapsulating  
3                   a semiconductor device, comprising: a) providing a semiconductor device;  
4                   b) providing a dispensing apparatus having a plurality of dispensing  
5                   orifices proximate the semiconductor device; and c) dispensing a liquid  
6                   encapsulating material through the plurality of orifices and over the  
7                   semiconductor device. In another aspect, the invention includes a  
8                   method of forming an electronic package, comprising: a) providing a  
9                   circuit board having a circuit pattern; b) joining a plurality of  
10                  semiconductor devices to the circuit board in electrical connection with  
11                  the circuit pattern; c) providing a dispensing apparatus having a plurality  
12                  of dispensing orifices proximate the semiconductor devices; d)  
13                  simultaneously dispensing liquid encapsulating material through at least  
14                  two of the plurality of orifices and over at least two of the  
15                  semiconductor devices; and e) curing the liquid encapsulating material.

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